

AMENDMENT(S) TO THE SPECIFICATION

Please replace the paragraph beginning at page 1, line 13, with the following rewritten paragraph:

In recent years, as the use of the Internet has increased, electronic apparatuses that use CPUs running at high clock frequencies in a sub-microwave band (0.3 to 10 GHz), electronic apparatuses that use high frequency bus, and telecommunication apparatuses that utilize radio waves have been increasing, such as personal computers, home appliances having information processing functions, wireless LAN, bluetooth-equipped apparatuses, optical module, mobile telephones, mobile information terminals and intelligent road traffic information system. This trend leads to a society of ubiquitous computing that requires devices of higher performance with high-speed digital information processing function and low-voltage driving. However, as such apparatuses become popular, concerns have been increasing on the problems related to the electromagnetic interference such as malfunctioning of an apparatus that emits electromagnetic radiation or other apparatuses and health threats to humans. For this reason, such an apparatus is required to minimize the emission of unnecessary electromagnetic radiation so as not to affect its own operation and that of other apparatuses and so as not to cause adverse effects on the human body, and to operate without malfunctioning when subjected to electromagnetic radiation emitted by other apparatuses. Measures to prevent such electromagnetic interference include the use of an electromagnetic radiation shielding material that reflects electromagnetic radiation and the use of an electromagnetic radiation absorbing material.

Please replace the paragraph beginning at page 19, line 12, with the following rewritten paragraph:

In this regard, the binding agent is preferably a thermosetting resin or a resin that is cured when exposed to an energy beam (ultraviolet light, electron beam) which allows it that the elastic modulus to be low during vapor deposition and can to be increased by crosslinking after the vapor deposition.